



# IMPORTANT NOTICE

10 December 2015

## 1. Global joint venture starts operations as WeEn Semiconductors

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As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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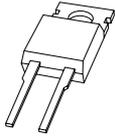
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Thank you for your cooperation and understanding,

WeEn Semiconductors





# BYC20-600

Rectifier diode, hyperfast

Rev. 01 — 28 November 2007

Product data sheet

## 1. Product profile

### 1.1 General description

Hyperfast, epitaxial rectifier diode in a SOD59 (2-lead TO-220AC) plastic package.

### 1.2 Features

- Extremely fast switching
- Reduces switching loss in associated MOSFET
- Low thermal resistance
- Low reverse recovery current

### 1.3 Applications

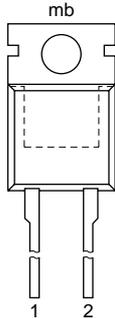
- Half-bridge or full-bridge switched-mode power supplies
- Half-bridge lighting ballasts
- Continuous Current Mode (CCM) Power Factor Correction (PFC)

### 1.4 Quick reference data

- $V_{RRM} \leq 600$  V
- $V_F = 1.54$  V (typ)
- $I_{F(AV)} \leq 20$  A
- $t_{rr} = 19$  ns (typ)

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode (k)		 001aaa020
2	anode (a)		
mb	mounting base; cathode		

SOD59 (2-lead TO-220AC)

### 3. Ordering information

**Table 2. Ordering information**

Type number	Package		Version
	Name	Description	
BYC20-600	TO-220AC	plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC	SOD59

### 4. Limiting values

**Table 3. Limiting values**

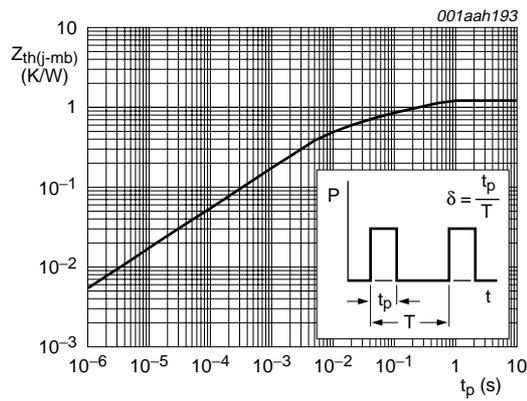
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	square waveform; $\delta = 1.0$ ; $T_{mb} \leq 100$ °C	-	500	V
$I_{F(AV)}$	average forward current	square waveform; $\delta = 0.5$ ; $T_{mb} \leq 93$ °C	-	20	A
$I_{FRM}$	repetitive peak forward current	square waveform; $\delta = 0.5$ ; $T_{mb} \leq 93$ °C; $t_p = 25$ $\mu$ s;	-	40	A
$I_{FSM}$	non-repetitive peak forward current	$t = 10$ ms; sinusoidal waveform	-	250	A
		$t = 8.3$ ms; sinusoidal waveform	-	274	A
$T_{stg}$	storage temperature		-40	+150	°C
$T_j$	junction temperature		-	150	°C

## 5. Thermal characteristics

**Table 4. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; see <a href="#">Figure 1</a>	-	-	1.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W



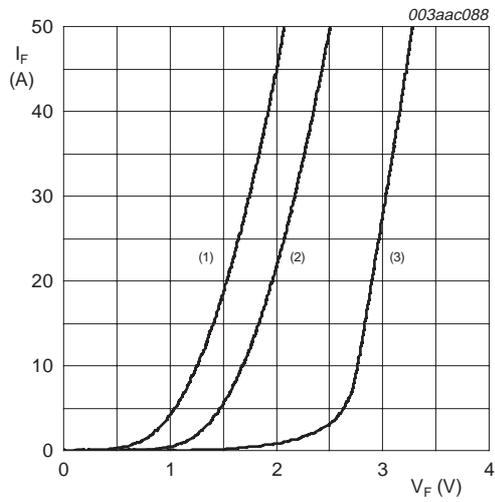
**Fig 1. Transient thermal impedance from junction to mounting base as a function of pulse width**

## 6. Characteristics

**Table 5. Characteristics**

$T_j = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 20\text{ A}$ ; $T_j = 150\text{ °C}$ ; see <a href="#">Figure 2</a>	-	1.54	1.97	V
		$I_F = 40\text{ A}$ ; $T_j = 150\text{ °C}$ ; see <a href="#">Figure 2</a>	-	1.95	2.34	V
		$I_F = 20\text{ A}$ ; see <a href="#">Figure 2</a>	-	1.89	2.9	V
$I_R$	reverse current	$V_R = 600\text{ V}$	-	16	200	$\mu\text{A}$
		$V_R = 500\text{ V}$ ; $T_j = 100\text{ °C}$	-	1.6	3.0	mA
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}$ to $V_R = 30\text{ V}$ ; $dI_F/dt = 50\text{ A}/\mu\text{s}$ ; see <a href="#">Figure 3</a>	-	35	55	ns
		$I_F = 20\text{ A}$ to $V_R = 400\text{ V}$ ; $dI_F/dt = 500\text{ A}/\mu\text{s}$ ; see <a href="#">Figure 3</a>	-			
		$T_j = 25\text{ °C}$	-	19	-	ns
		$T_j = 100\text{ °C}$	-	32	40	ns
$I_{RM}$	peak reverse recovery current	$I_F = 20\text{ A}$ to $V_R = 400\text{ V}$ ; $T_j = 125\text{ °C}$ ; see <a href="#">Figure 3</a>	-			
		$dI_F/dt = 50\text{ A}/\mu\text{s}$	-	3.0	7.5	A
		$dI_F/dt = 500\text{ A}/\mu\text{s}$	-	9.5	12	A
$V_{FR}$	forward recovery voltage	$I_F = 20\text{ A}$ ; $dI_F/dt = 100\text{ A}/\mu\text{s}$ ; see <a href="#">Figure 4</a>	-	8	11	V



- (1)  $T_j = 150\text{ }^\circ\text{C}$ ; typical values
- (2)  $T_j = 150\text{ }^\circ\text{C}$ ; maximum values
- (3)  $T_j = 25\text{ }^\circ\text{C}$ ; maximum values

Fig 2. Forward current as a function of forward voltage

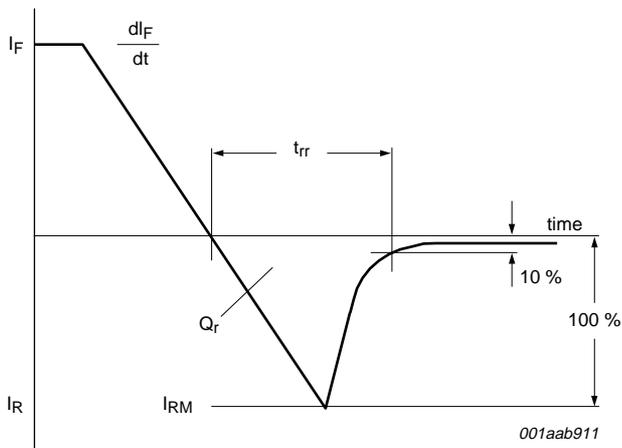


Fig 3. Reverse recovery definitions

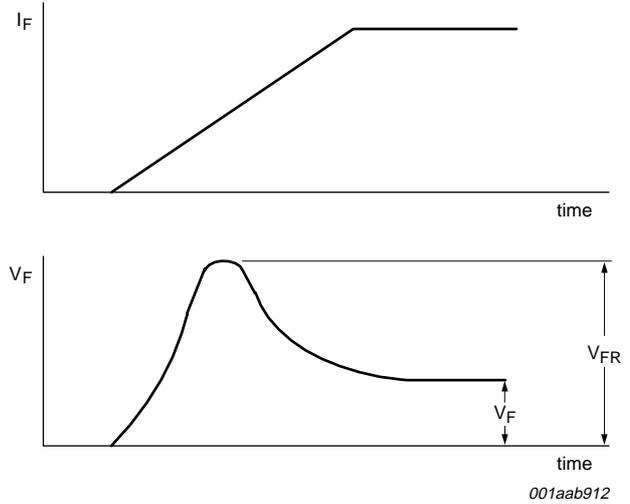
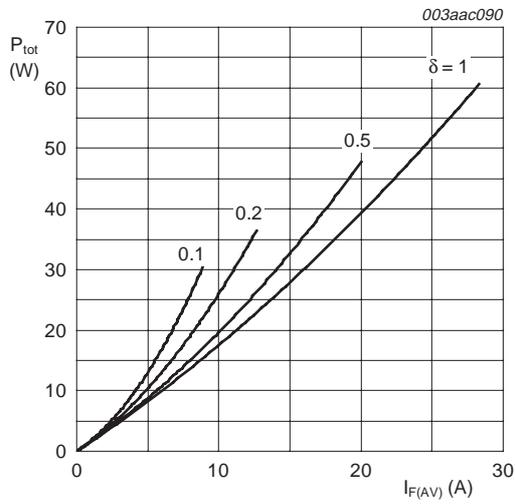
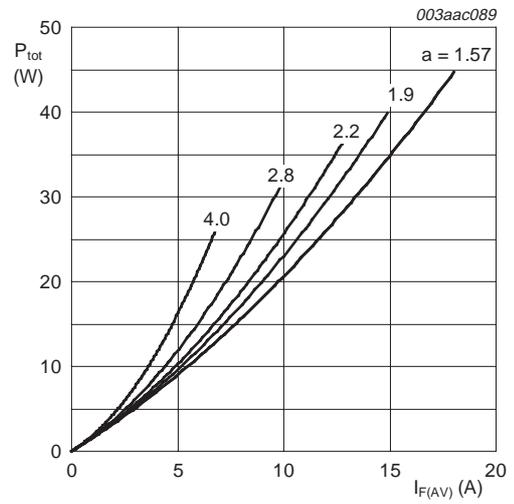


Fig 4. Forward recovery definitions



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

**Fig 5. Forward power dissipation as a function of average forward current; square waveform; maximum values**



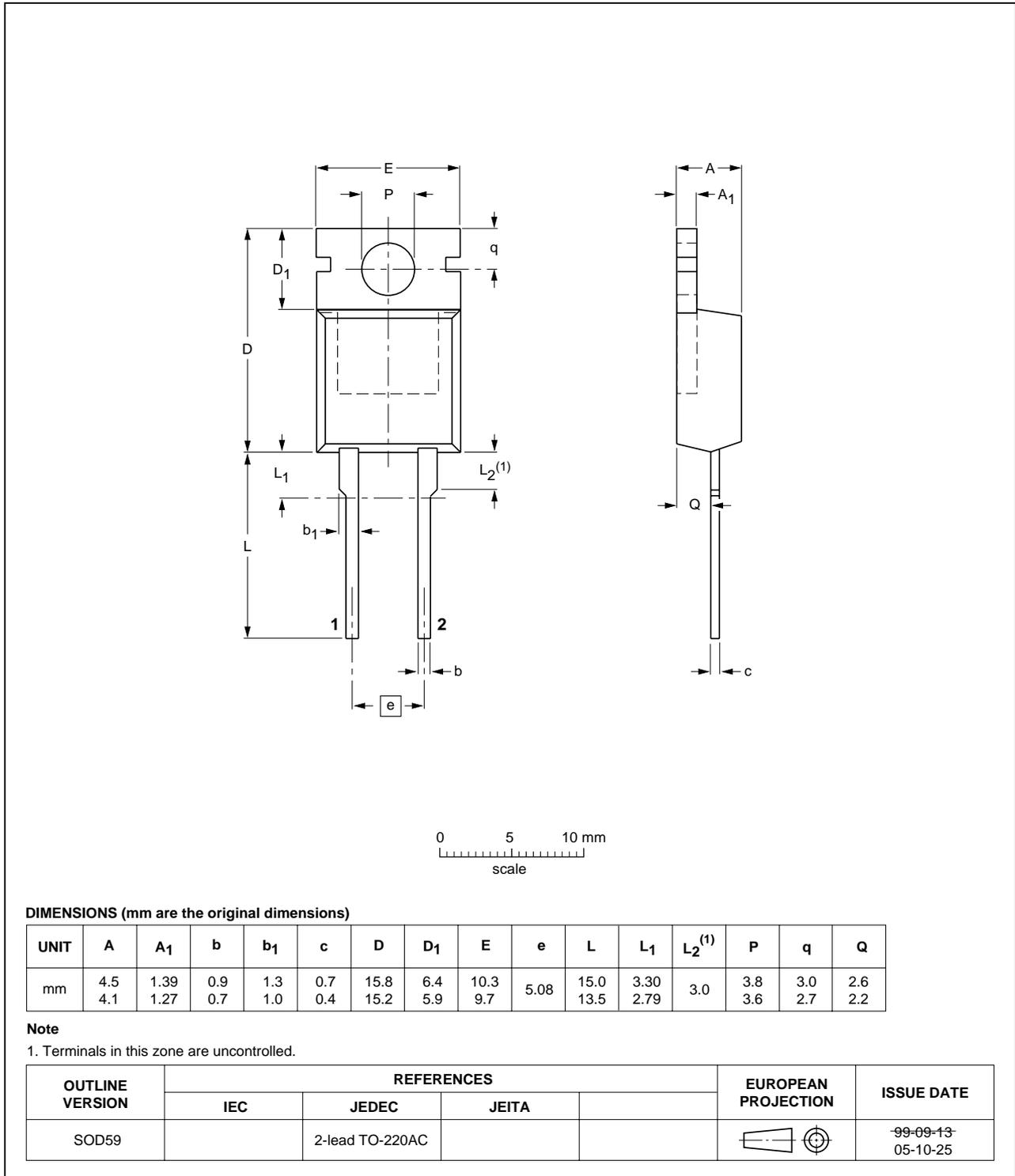
$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

**Fig 6. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**

**7. Package outline**

Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC

SOD59



**Fig 7. Package outline SOD59 (2-lead TO-220AC)**

## 8. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BYC20-600_1	20071128	Product data sheet	-	-

## 9. Legal information

### 9.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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